

Patterning Aware Design Optimization of Selective Etching in N5 and Beyond

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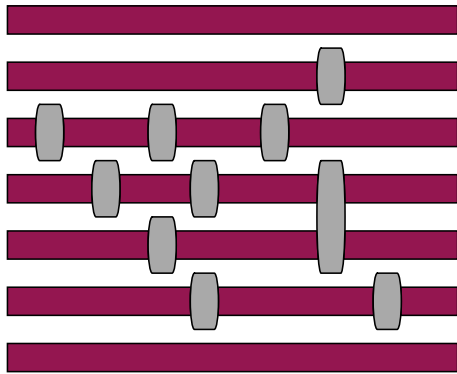
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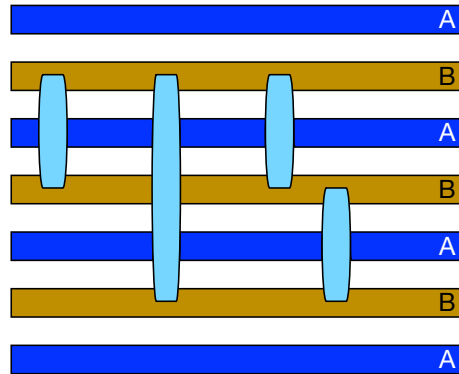
Conventional Blocks v.s. Self-Aligned Blocks (SAB)



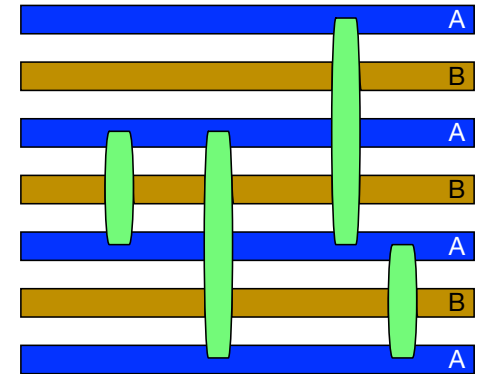
Two approaches to obtain equivalent patterns



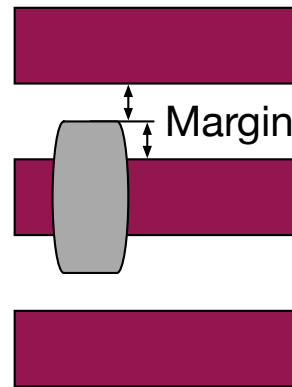
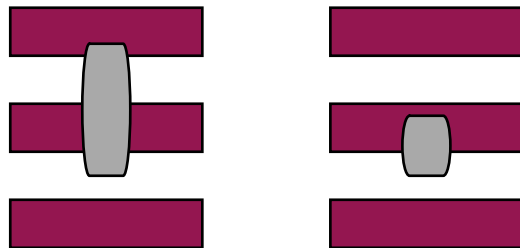
Conventional blocks



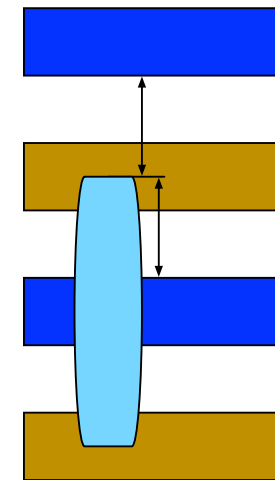
SAB enabled by selective etching



Process variation



$$\text{EPE margin} = \frac{1}{4}P$$



$$\text{EPE margin} = \frac{3}{4}P$$

EPE margin: margin to tolerate edge placement error

Problem Formulation



How large is the **design space** for SAB?

How to enable **fast design closure** for SAB?

Design rule exploration

- Given lithography options of SAB and technology definitions
- e.g., pitches and lithography spacing for blocks
- Define design rules with maximum solution space for design closure

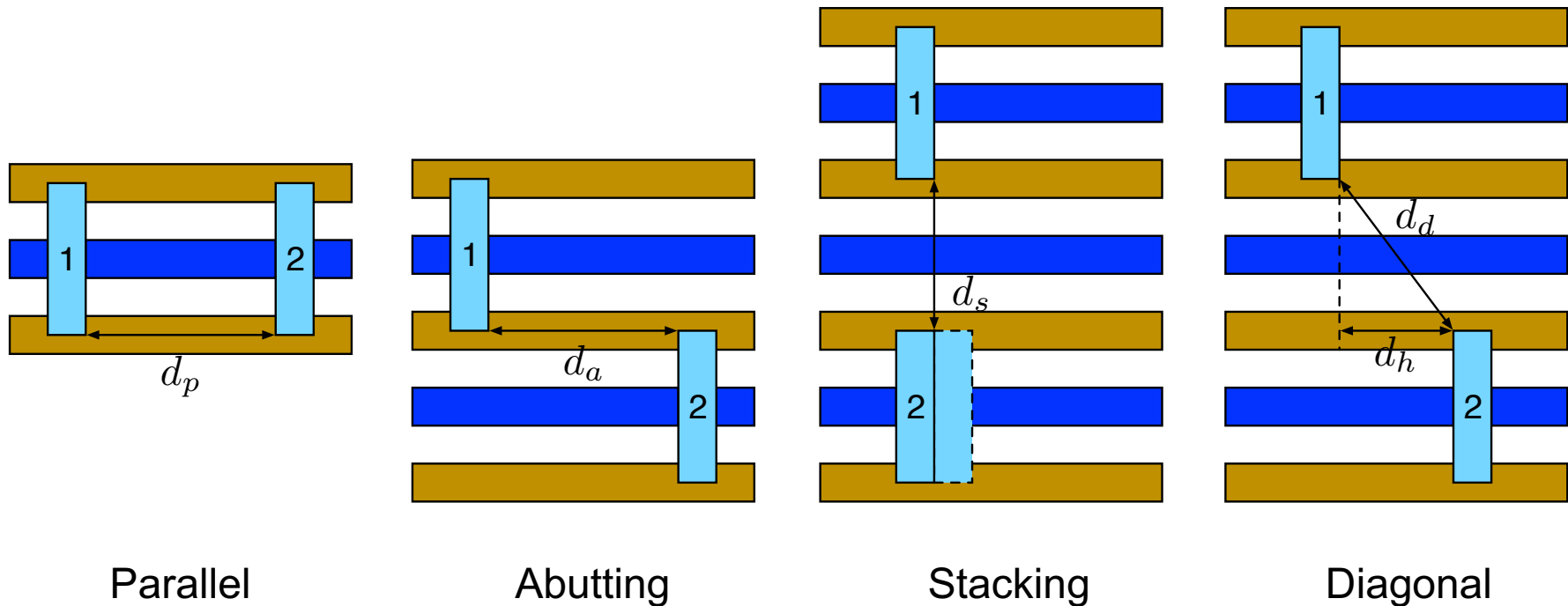
SAB mask optimization

- Given a set of design rules and designs
- Optimize blocks by redistribution to remove design rule violations
- Perform layout decomposition of blocks
- Minimize cost of redistribution, such as total line end extension

Patterns That Cause Conflicts

4 types of patterns that may result in conflicts

- Spacing rules



| Patterns | Parallel | Abutting | Stacking | Diagonal |
|-------------------|----------|----------|----------|------------|
| Required Distance | d_p | d_a | d_s | d_d, d_h |

Simple and Complex Rules for SAB



Link design rules to line pitch P and lithography spacing s

Simple rules

- $d_p = d_a = d_s = d_d$

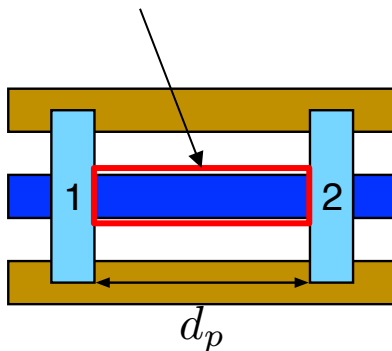
Limited by **parallel** patterns

- Minimum area constraint
- Lithography spacing

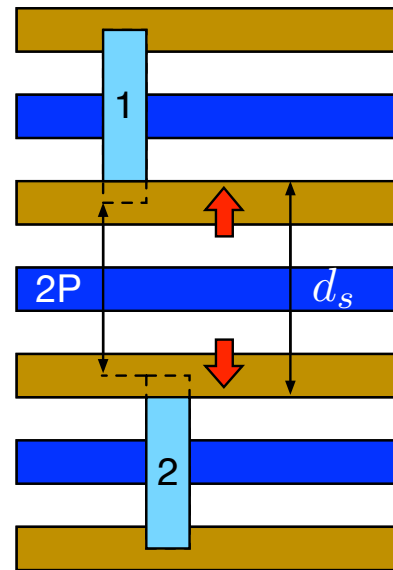
Complex rules

- Allow different d_p, d_a, d_s, d_d
- **NEGATIVE block end extension** to enable **stacking** patterns

Minimum area constraint



Parallel



Stacking

If $2P < d_s = s$

Tradeoff EPE margin for design space

Simple and Complex Rules for SAB



Link design rules to line pitch P and lithography spacing s

Simple rules

- $d_p = d_a = d_s = d_d$

Complex rules

- Allow different d_p, d_a, d_s, d_d
- **NEGATIVE block end extension** to enable **stacking** patterns

Assume **8nm** EPE margin required [Han+,SPIE2016]

| | | Conventional block | SAB simple rules | SAB complex rules |
|-----|-----|--------------------|------------------|-------------------|
| P | s | margin | margin | margin |
| 24 | 84 | 6 | 18 | 0 |
| | 80 | | | 2 |
| 28 | 84 | 7 | 21 | 7 |
| | 80 | | | 9 |
| 32 | 84 | 8 | 24 | 14 |
| | 80 | | | 16 |
| 36 | 84 | 9 | 27 | 21 |
| | 80 | | | 23 |

Approx. **N5**

Can **complex rules** enable larger design space than **simple rules**?

Conclusion



Design space exploration for SAB

- Design rules scalable with pitches and lithography spacing
- Post optimization for SAB
- Impacts of design rules to design closure

SAB is a promising and feasible option for N5 and beyond

- Provide insights to the further advancement of manufacturing process

Future work

- SAB friendly design flow
- Early stage consideration of SAB rules



Thank you

Outline

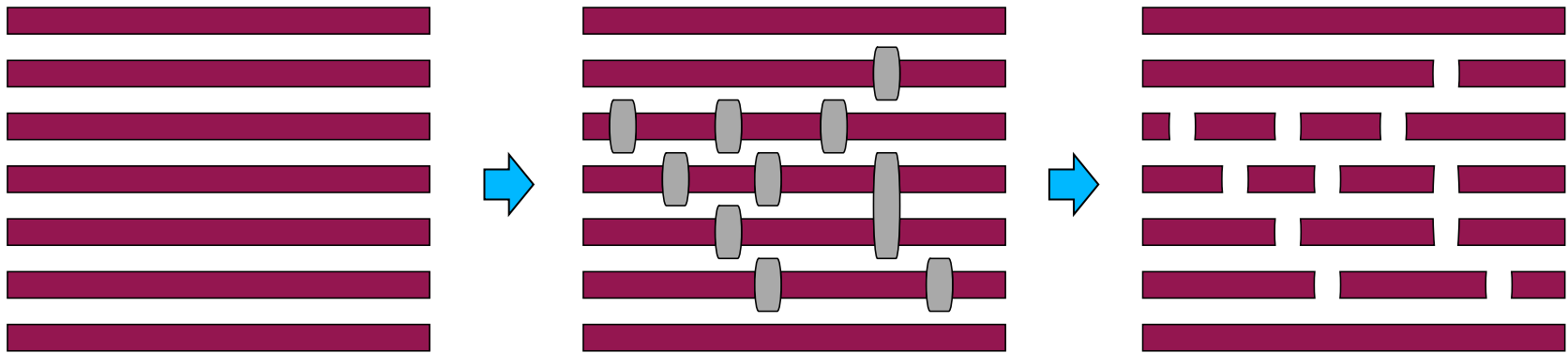


- Introduction
- Problem Formulation
- SAB Design Rule Exploration
- SAB Optimization
- Conclusion

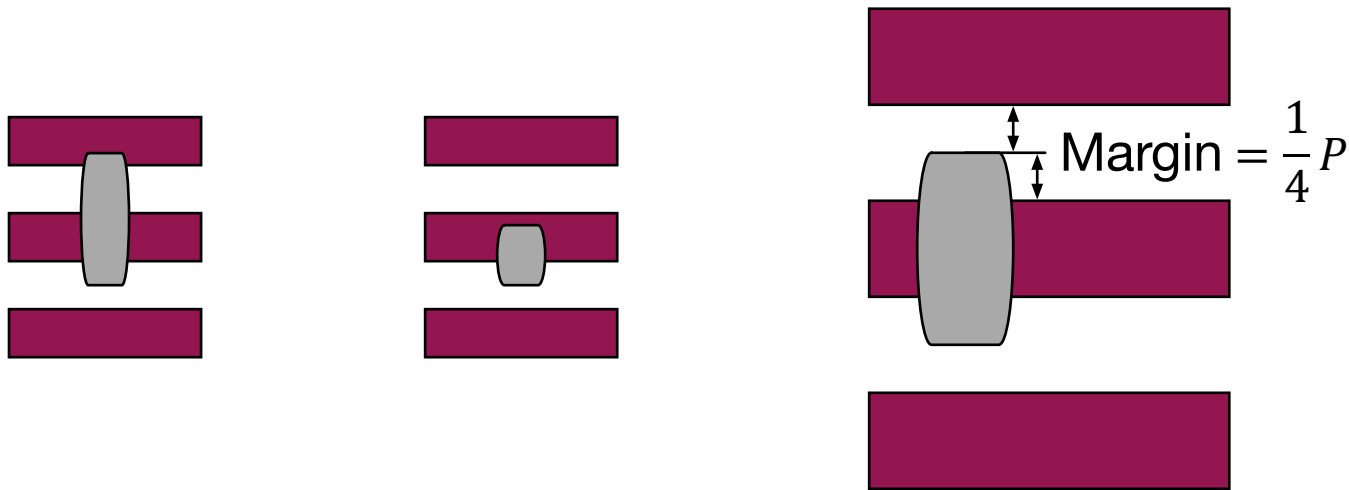
1-D Gridded Layout – Lines and Blocks



Conventional blocks (cuts)



Process variation

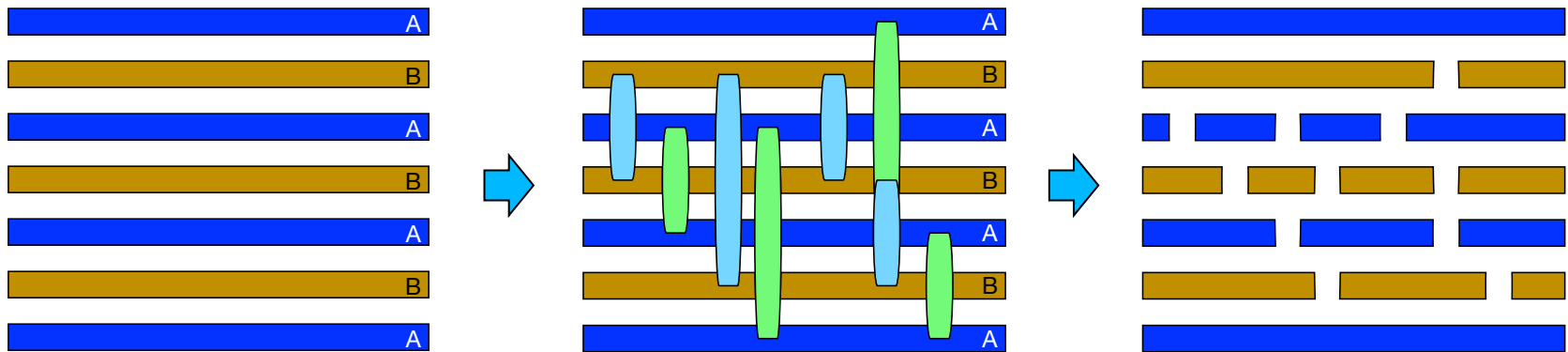


EPE margin: margin to tolerate edge placement error

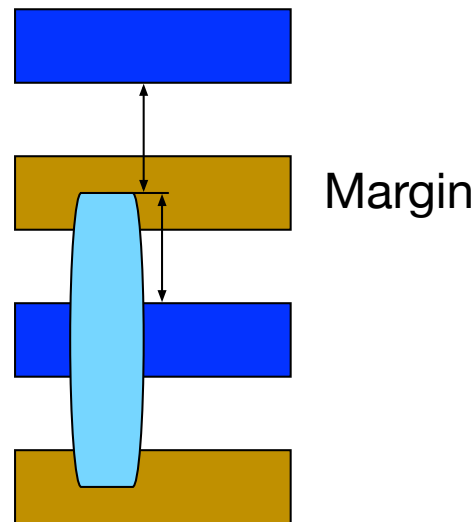
1-D Gridded Layout – SAB Lines and Blocks



Self-aligned blocks (SAB)

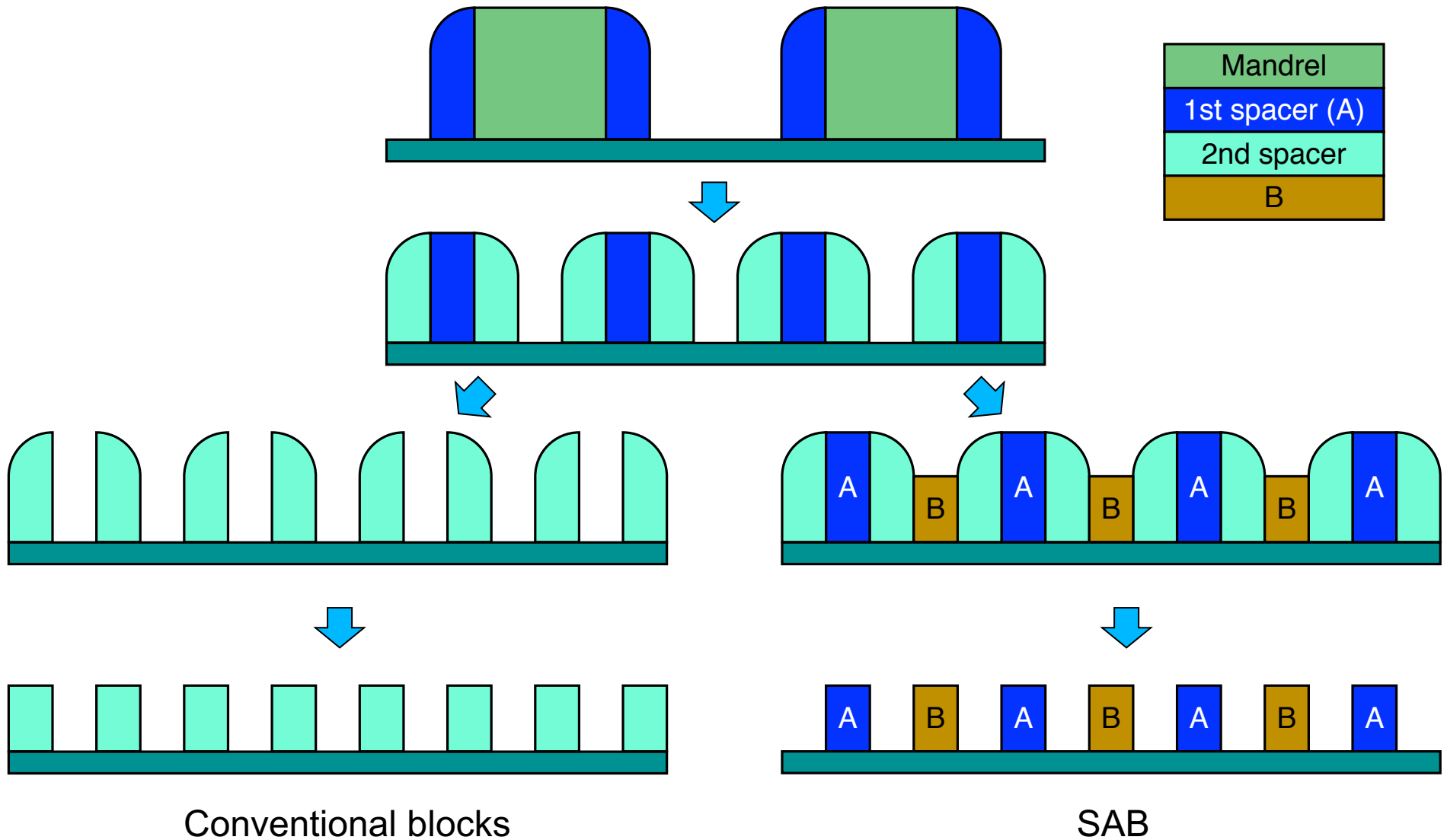


$$\text{EPE margin} = \frac{3}{4}P$$



Manufacturing Process of SAB

Non-selective etching v.s. selective etching

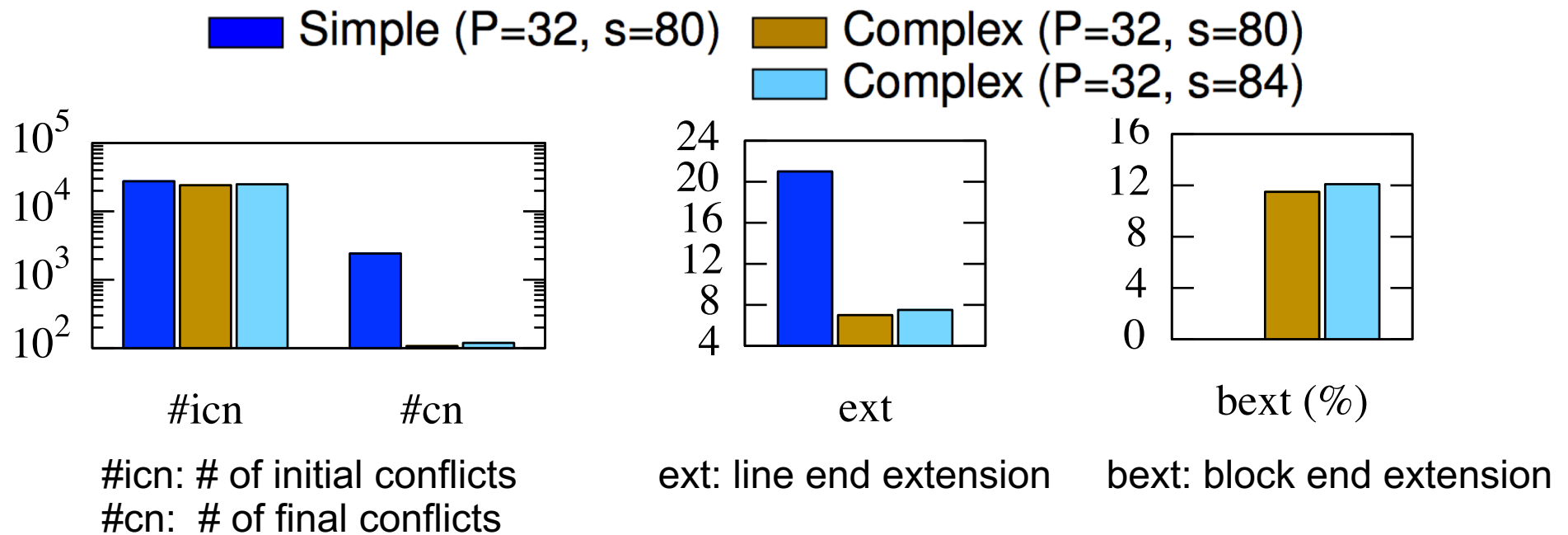


SAB Optimization



SAB redistribution to resolve conflicts

- A post optimization stage in existing physical design flow
- Simple rules v.s. complex rules



- Simple rules results in 22x more final conflicts than complex rules
- Relaxing lithography spacing results in 10% more final conflicts